



PHOTOCOUPLER

PS2561D-1, PS2561DL-1

PS2561DL1-1, PS2561DL2-1

DIP PHOTOCOUPLER

OPERATING AMBIENT TEMPERATURE 110°C

–NEPOC Series–

DESCRIPTION

The PS2561D-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

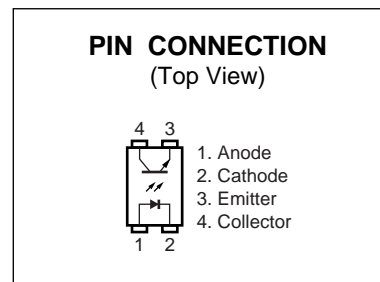
The PS2561D-1 is in a plastic DIP (Dual In-line Package) and the PS2561DL-1 is lead bending type (Gull-wing) for surface mount.

The PS2561DL1-1 is lead bending type for long creepage distance.

The PS2561DL2-1 is lead bending type for long creepage distance (Gull-wing) for surface mount.

FEATURES

- Operating ambient temperature: 110°C
- High Isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage ($V_{CE0} = 80\text{ V}$)
- High current transfer ratio (CTR = 160% TYP.)
- High-speed switching ($t_r = 3\ \mu\text{s}$ TYP., $t_f = 5\ \mu\text{s}$ TYP.)
- Ordering number of taping product: PS2561DL-1-F3 : 2 000 pcs/reel
: PS2561DL2-1-E3: 1 000 pcs/reel
- Pb-Free product
- ★ Safety standards
 - UL approved: No. E72422
 - CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
 - BSI approved: No. 7112/7420
 - SEMKO approved: No. 903238
 - NEMKO approved: No. P09210868
 - DEMKO approved: No. 314999
 - FIMKO approved: No. FI 25119
 - DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40008862 (Option)



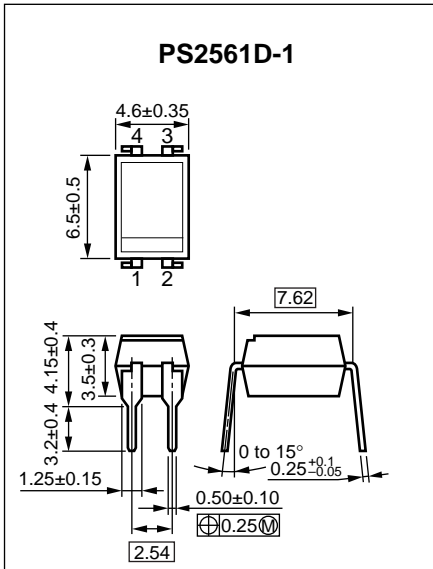
APPLICATIONS

- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

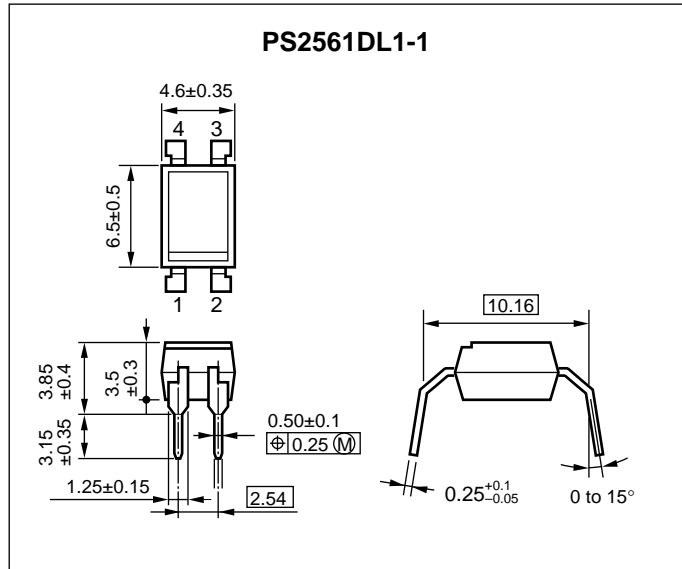
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PACKAGE DIMENSIONS (UNIT : mm)

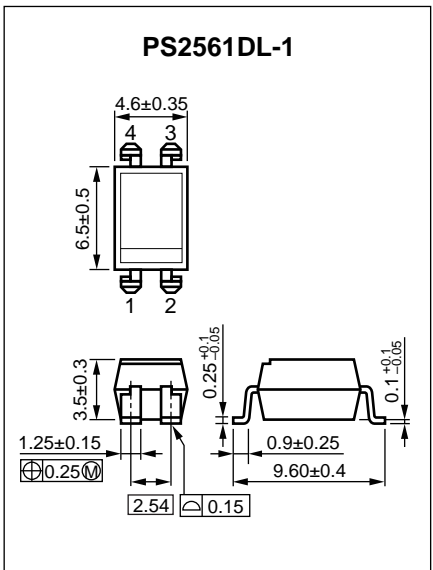
DIP Type



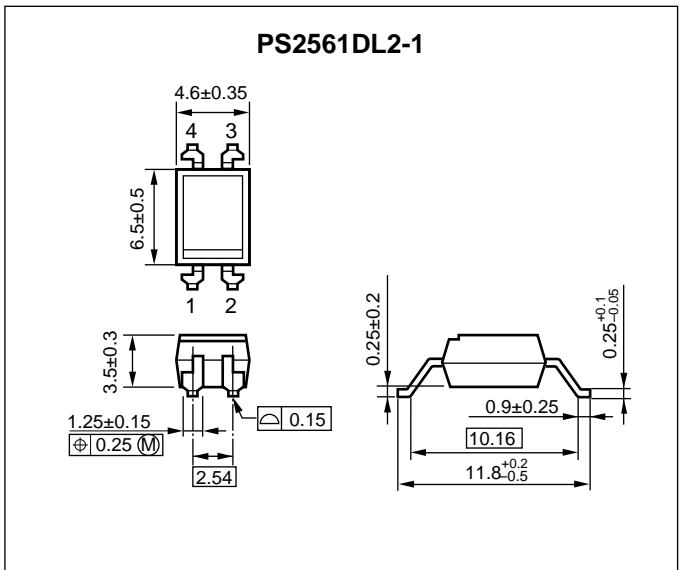
Long Creepage Distance



★ Lead Bending Type



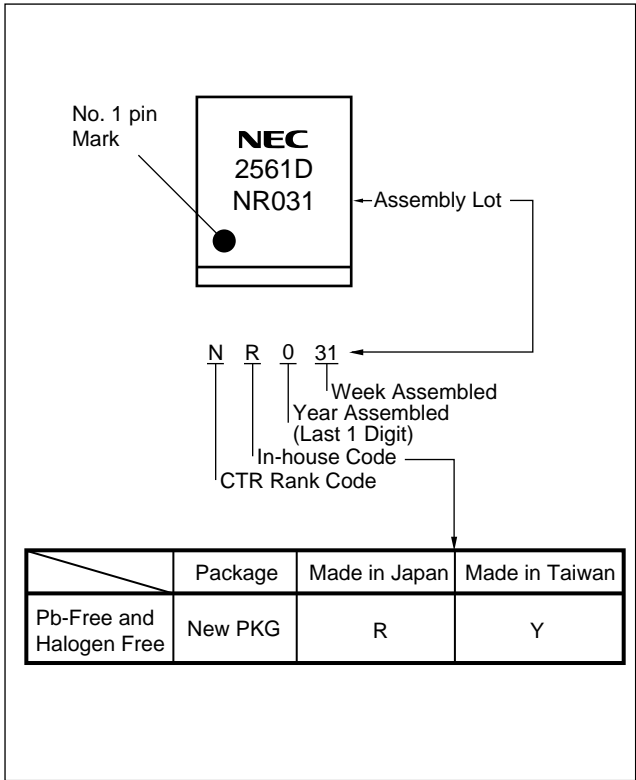
Long Creepage Distance (Gull-Wing)



PHOTOCOUPLER CONSTRUCTION

Parameter	PS2561D-1, PS2561DL-1	PS2561DL1-1, PS2561DL2-1
Air Distance (MIN.)	7 mm	8 mm
Outer Creepage Distance (MIN.)	7 mm	8 mm
Inner Creepage Distance (MIN.)	4 mm	4 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

★ **MARKING EXAMPLE**



★ **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *1		
PS2561D-1	PS2561D-1Y-A	Special version (Pb-Free and Halogen Free)	Magazine case 100 pcs	Standard products (UL, CSA, BSI, NEMKO, DEMKO, SEMKO, FIMKO approved)	PS2561D-1		
PS2561DL-1	PS2561DL-1Y-A				PS2561DL-1		
PS2561DL1-1	PS2561DL1-1Y-A				PS2561DL1-1		
PS2561DL2-1	PS2561DL2-1Y-A				PS2561DL2-1		
PS2561DL-1-F3	PS2561DL-1Y-F3-A		Embossed Tape 2 000 pcs/reel		PS2561DL-1		
PS2561DL2-1-E3	PS2561DL2-1Y-E3-A		Embossed Tape 1 000 pcs/reel		PS2561DL2-1		
PS2561D-1-V	PS2561D-1Y-V-A		Magazine case 100 pcs		DIN EN60747-5-2 (VDE0884 Part2) approved (Option)	PS2561D-1	
PS2561DL-1-V	PS2561DL-1Y-V-A					PS2561DL-1	
PS2561DL1-1-V	PS2561DL1-1Y-V-A					PS2561DL1-1	
PS2561DL2-1-V	PS2561DL2-1Y-V-A					PS2561DL2-1	
PS2561DL-1-V-F3	PS2561DL-1Y-V-F3-A					Embossed Tape 2 000 pcs/reel	PS2561DL-1
PS2561DL2-1-V-E3	PS2561DL2-1Y-V-E3-A					Embossed Tape 1 000 pcs/reel	PS2561DL2-1

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage	V _R	6	V
	Forward Current (DC)	I _F	40	mA
	Power Dissipation Derating	ΔP _D /°C	1.5	mW/°C
	Power Dissipation	P _D	150	mW
	Peak Forward Current ^{*1}	I _{FP}	1	A
Transistor	Collector to Emitter Voltage	V _{CEO}	80	V
	Emitter to Collector Voltage	V _{ECO}	7	V
	Collector Current	I _C	50	mA
	Power Dissipation Derating	ΔP _C /°C	1.5	mW/°C
	Power Dissipation	P _C	150	mW
Isolation Voltage ^{*2}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +110	°C
Storage Temperature		T _{stg}	-55 to +150	°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.

Pins 1-2 shorted together, 3-4 shorted together.

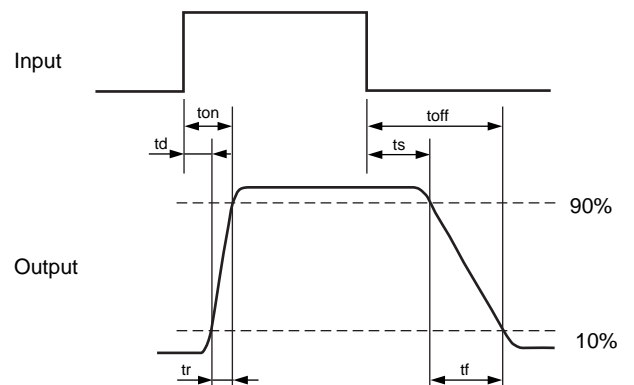
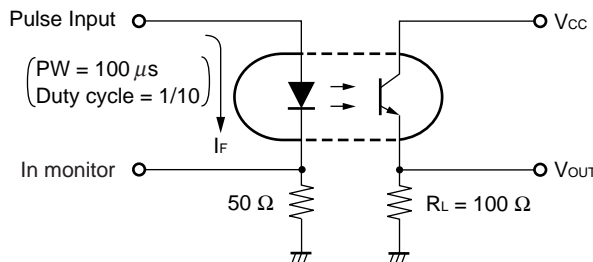
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.2	1.4	V
	Reverse Current	I _R	V _R = 5 V			5	μA
	Terminal Capacitance	C _t	V = 0 V, f = 1.0 MHz		10		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	V _{CE} = 48 V, I _F = 0 mA			100	nA
Coupled	Current Transfer Ratio (I _c /I _F) ^{*1}	CTR	I _F = 5 mA, V _{CE} = 5 V	50	160	400	%
			I _F = 1 mA, V _{CE} = 5 V	10	80		
	Collector Saturation Voltage	V _{CE(sat)}	I _F = 10 mA, I _c = 2 mA			0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time ^{*2}	t _r	V _{CC} = 10 V, I _c = 2 mA, R _L = 100 Ω		3		μs
	Fall Time ^{*2}	t _f			5		

*1 CTR rank

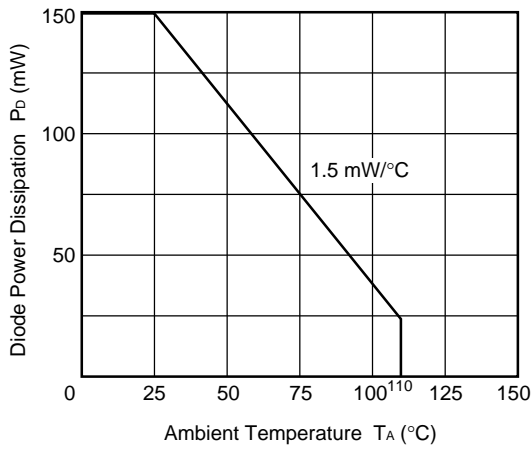
CTR Rank	CTR (%)	Conditions
H	80 to 160	I _F = 5 mA, V _{CE} = 5 V
	16 and larger	I _F = 1 mA, V _{CE} = 5 V
Q	100 to 200	I _F = 5 mA, V _{CE} = 5 V
	20 and larger	I _F = 1 mA, V _{CE} = 5 V
W	130 to 260	I _F = 5 mA, V _{CE} = 5 V
	26 and larger	I _F = 1 mA, V _{CE} = 5 V
L	200 to 400	I _F = 5 mA, V _{CE} = 5 V
	40 and larger	I _F = 1 mA, V _{CE} = 5 V
N	50 to 400	I _F = 5 mA, V _{CE} = 5 V
	10 and larger	I _F = 1 mA, V _{CE} = 5 V

★ *2 Test circuit for switching time

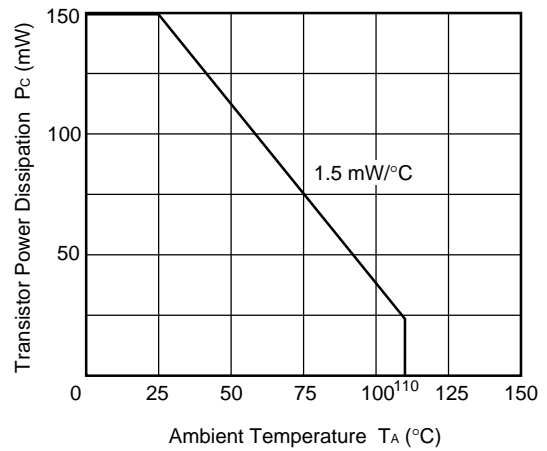


★ TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

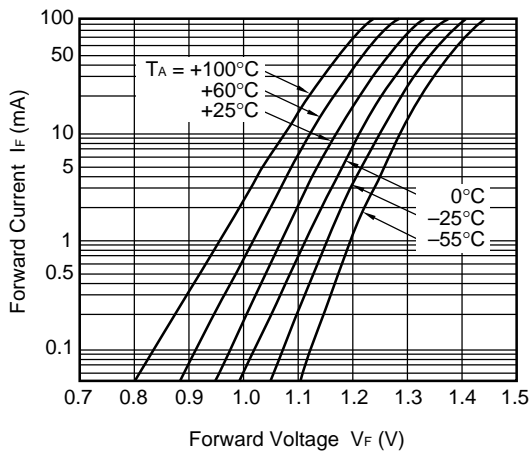
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



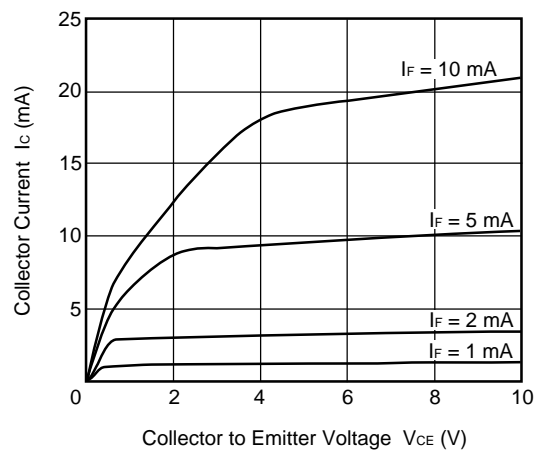
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



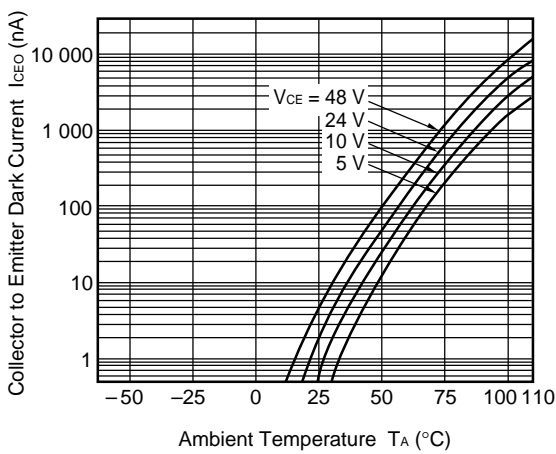
FORWARD CURRENT vs. FORWARD VOLTAGE



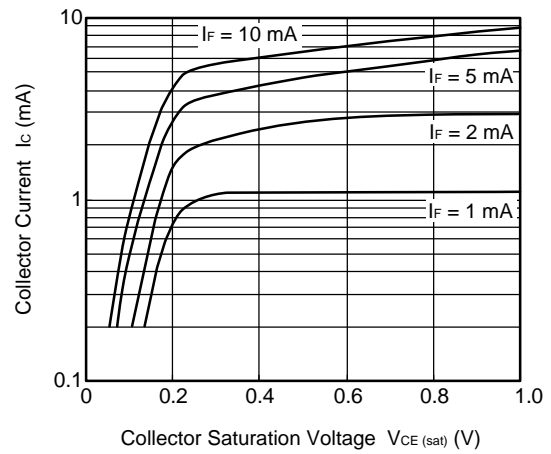
COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

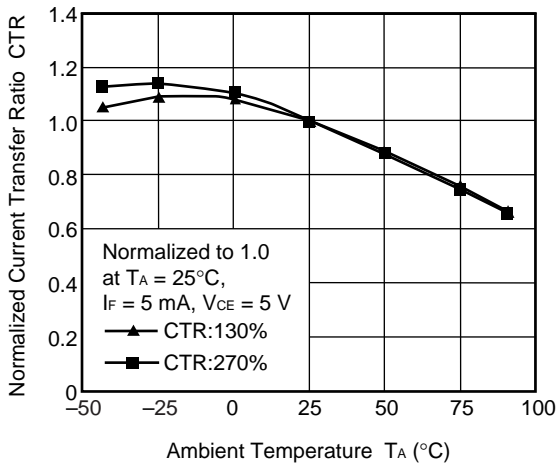


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

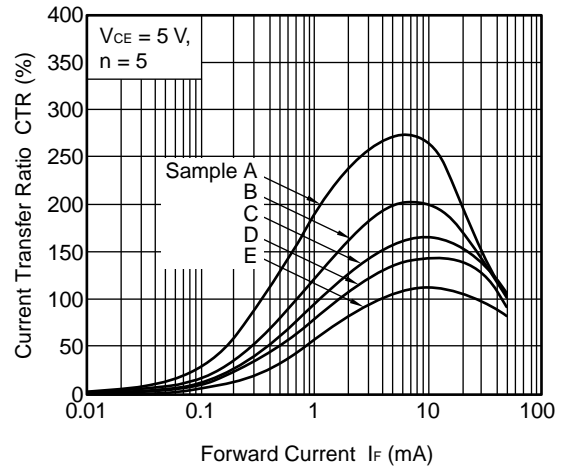


Remark The graphs indicate nominal characteristics.

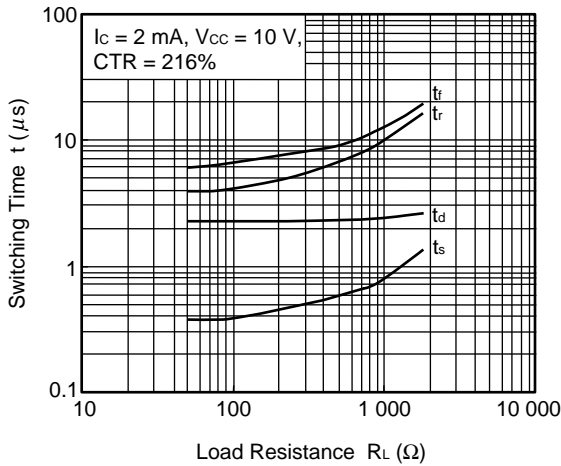
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



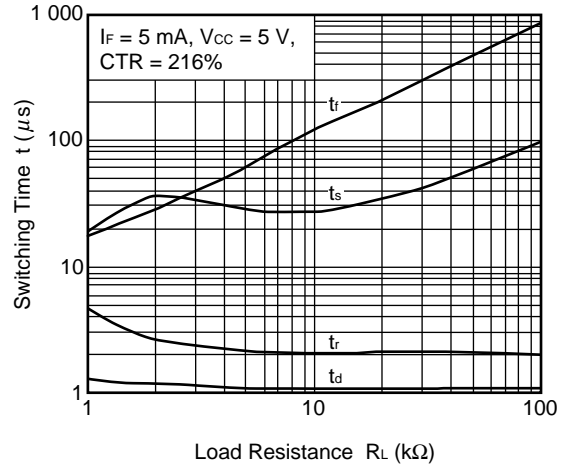
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



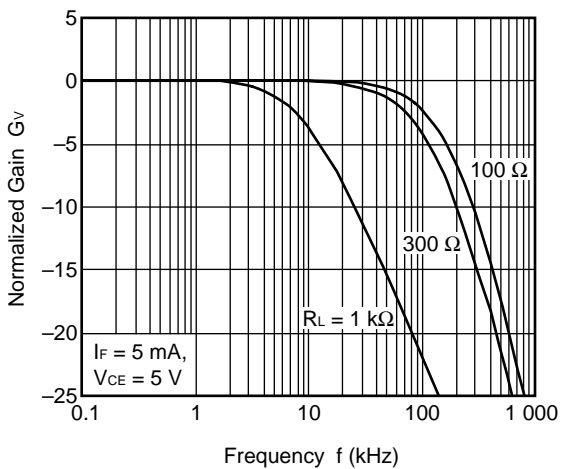
SWITCHING TIME vs. LOAD RESISTANCE



SWITCHING TIME vs. LOAD RESISTANCE



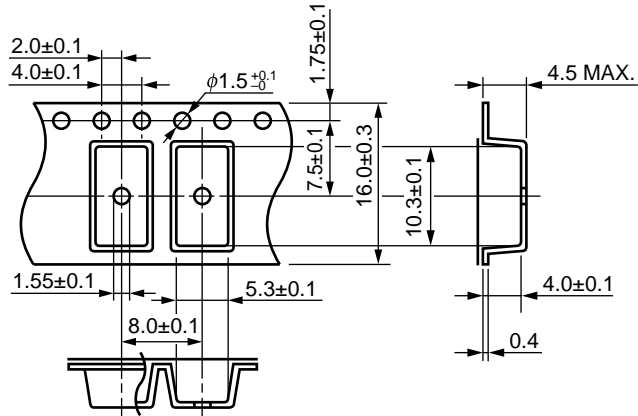
FREQUENCY RESPONSE



Remark The graphs indicate nominal characteristics.

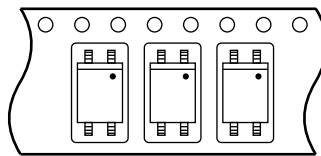
TAPING SPECIFICATIONS (UNIT : mm)

Outline and Dimensions (Tape)

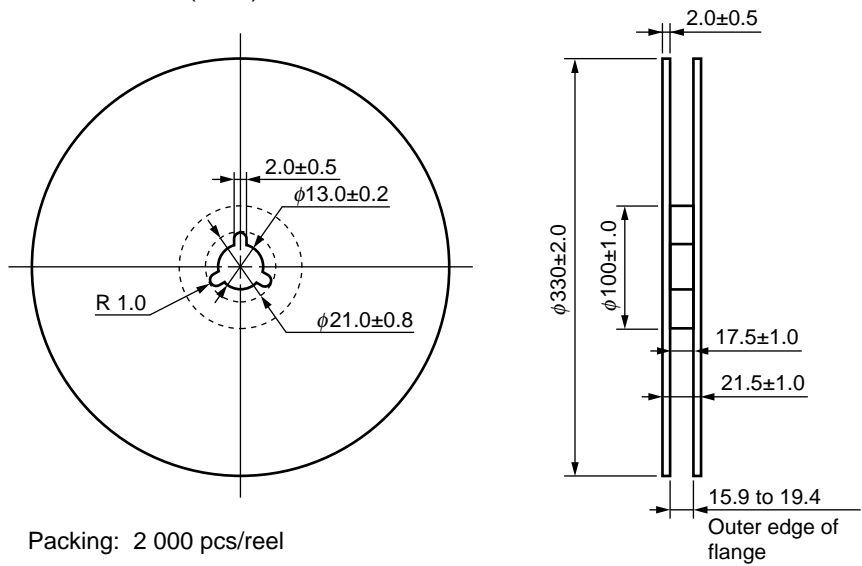


Tape Direction

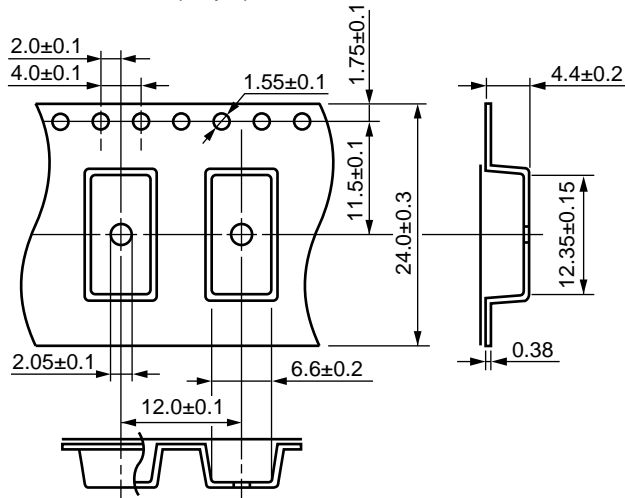
PS2561DL-1-F3



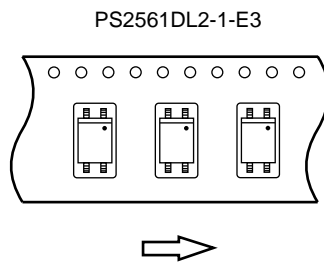
Outline and Dimensions (Reel)



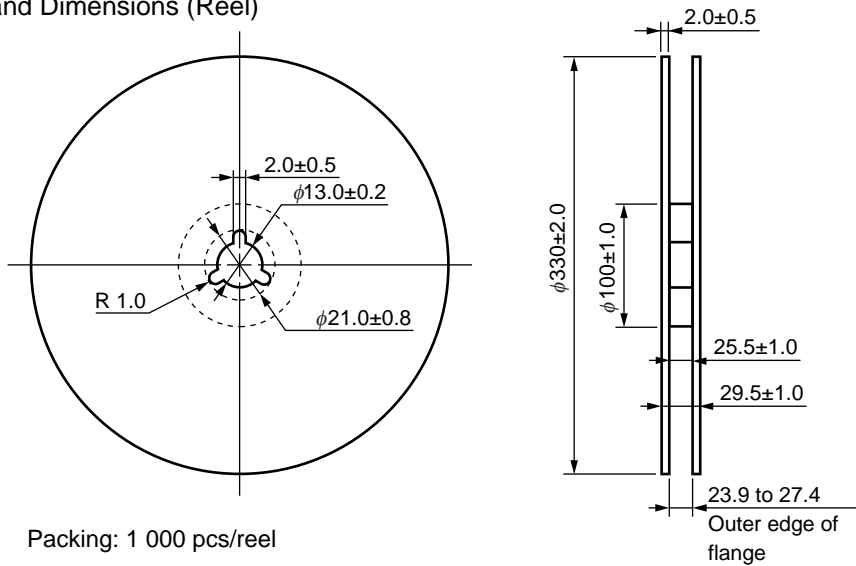
Outline and Dimensions (Tape)



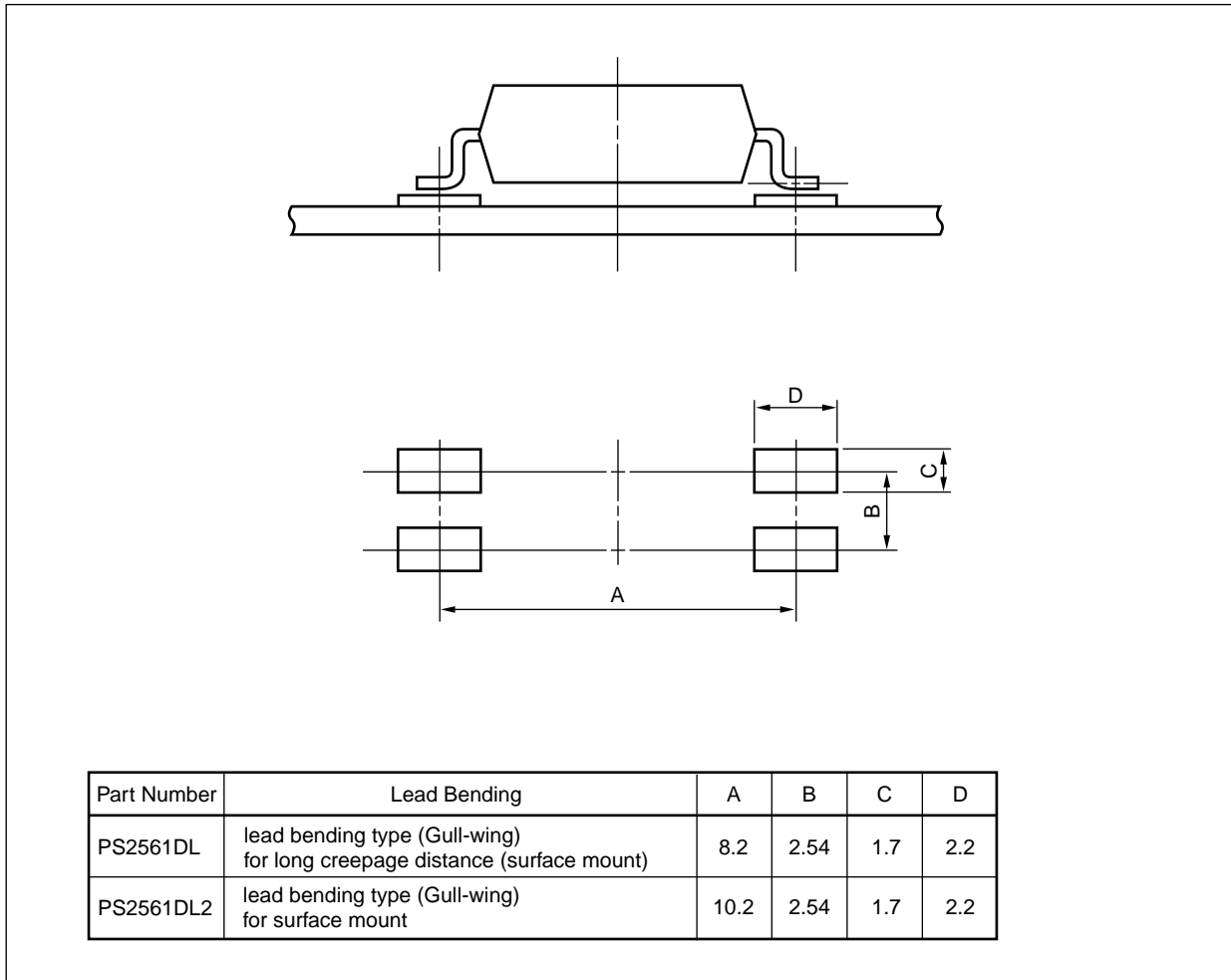
Tape Direction



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



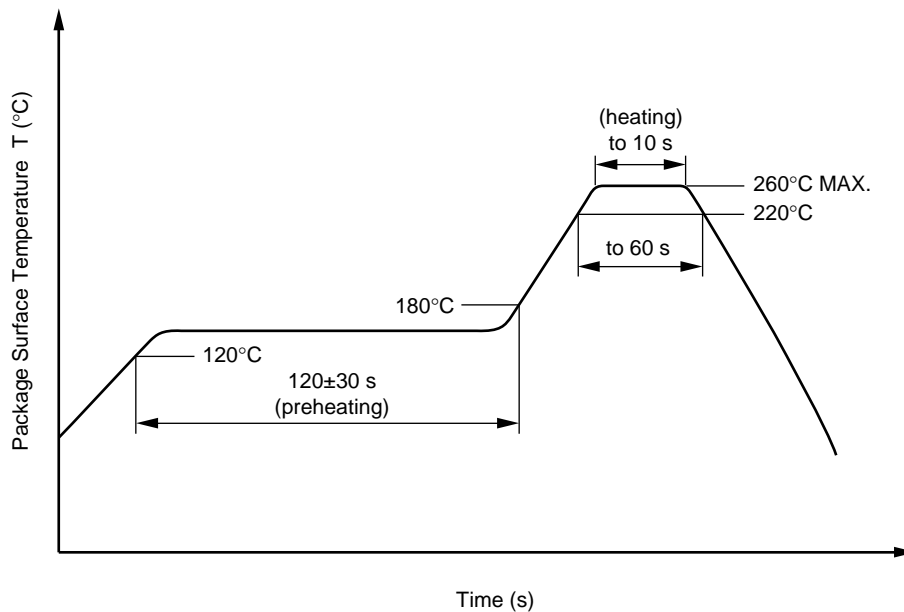
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between corrector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

★ **SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (1/2) (PS2561D-1, PS2561DL-1)**

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/110/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}, P_d < 5 \text{ pC}$	U_{IORM} U_{pr}	890 1 335	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}, P_d < 5 \text{ pC}$	U_{pr}	1 669	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +150	°C
Operating temperature range	T_A	-55 to +110	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25^\circ\text{C}$ $V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100^\circ\text{C}$	Ris MIN. Ris MIN.	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , $P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500 \text{ V dc at } T_A = T_{si}$	T_{si} I_{si} P_{si} Ris MIN.	175 400 700 10^9	°C mA mW Ω

★ **SPECIFICATION OF VDE MARKS LICENSE DOCUMENT (2/2) (PS2561DL1-1, PS2561DL2-1)**

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/110/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}, P_d < 5 \text{ pC}$	U_{IORM} U_{pr}	1 130 1 695	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}, P_d < 5 \text{ pC}$	U_{pr}	2 119	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
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- (2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).

M8E0904E

Caution	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none">• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.<ol style="list-style-type: none">1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.• Do not burn, destroy, cut, crush, or chemically dissolve the product.• Do not lick the product or in any way allow it to enter the mouth.
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